



March 2018
MBU-18-0203

TOSHIBA 4GB 15nm eMMC Product Change Notification

Toshiba Memory would like to announce the embedded controller wafer fabrication change for our 4GB eMMC product. We are changing the eMMC controller production site from Sony Semiconductor Manufacturing Corporation Oita Technology Center (SCK) to Taiwan Semiconductor Manufacturing Company Limited (TSMC) because of the controller production discontinuation at SCK. The performance and functionality (firmware) are fully identical.

1. Part # Impacted:

Current Part Number	New Part Number	Package
THGBMDG5D1LBAIT	THGBMNG5D1LBAIT	11.0x10.0x0.8mm (max)
THGBMDG5D1LBAIL	THGBMNG5D1LBAIL	11.5x13.0x0.8mm(max)

2. Schedule:

PCN Announcement	March 2018
LTB (Last Time Buy) of current part	June 30, 2018
LTS (Last Time Ship) of current part	September 30, 2018

Data Sheets/Samples of new part available	March 2018
Mass Production of new part available	April 2018 onwards

Please contact your sales representative to request data sheets and samples of new part.
Thank you for the implementation of this change.

Toshiba Memory America, Inc.

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